74HC257-Q100; 74HCT257-Q100

Quad 2-input multiplexer; 3-state

Rev. 1 — 27 July 2015 Product data sheet

1. General description

The 74HC257-Q100; 74HCT257-Q100 is a quad 2-input multiplexer with 3-state outputs. Inputs include clamp diodes. It enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC}.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - Specified from –40 °C to +85 °C and from –40 °C to +125 °C
- Non-inverting data path
- 3-state outputs interface directly with system bus
- Complies with JEDEC standard no. 7A
- Input levels:
  - For 74HC257: CMOS level
  - For 74HCT257: TTL level
- ESD protection:
  - MIL-STD-883, method 3015 exceeds 2000 V
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)
- Specified from –40 °C to +85 °C and from –40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC257D-Q100	–40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT257D-Q100				
74HC257PW-Q100	–40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT257PW-Q100				

4. Functional diagram

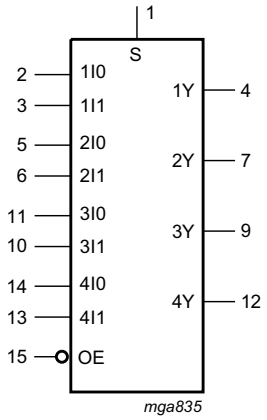


Fig 1. Logic symbol

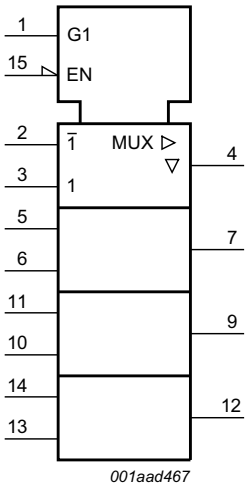


Fig 2. IEC logic symbol

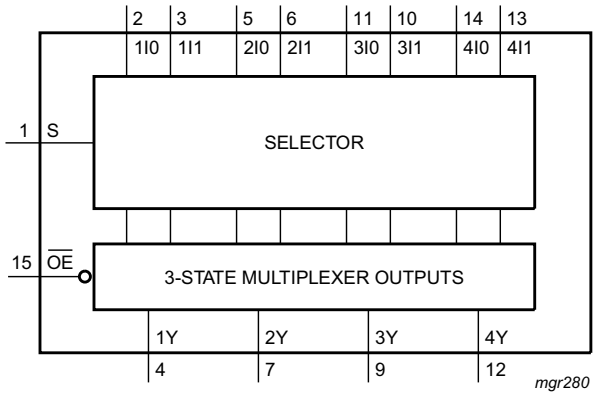


Fig 3. Functional diagram

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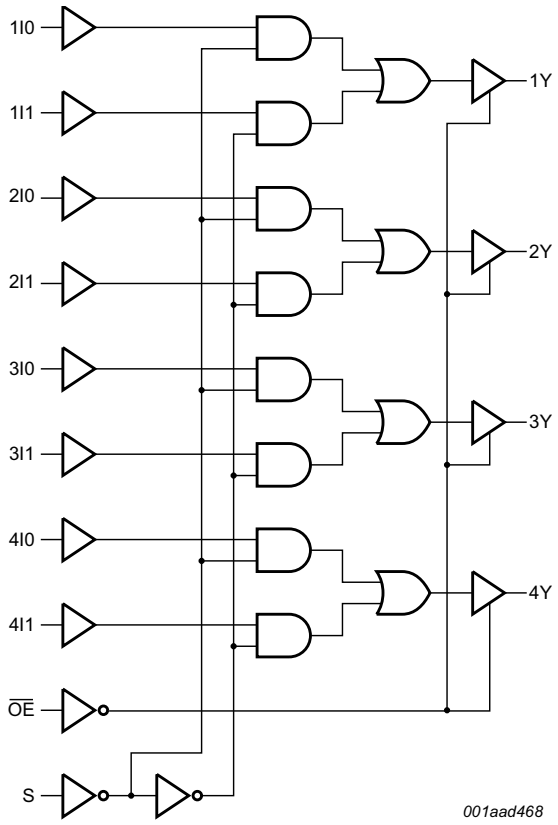


Fig 4. Logic diagram

5. Pinning information

5.1 Pinning

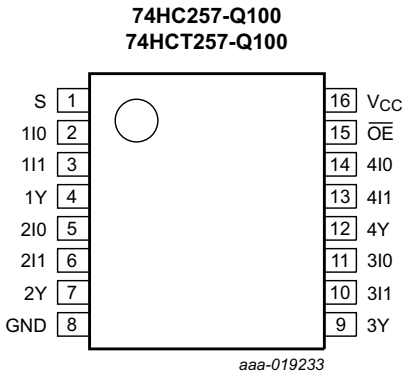


Fig 5. Pin configuration SO16 and TSSOP16

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5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
S	1	common data select input
1I0 to 4I0	2, 5, 11, 14	data input from source 0
1I1 to 4I1	3, 6, 10, 13	data input from source 1
1Y to 4Y	4, 7, 9, 12	3-state multiplexer output
GND	8	ground (0 V)
$\overline{OE}$	15	3-state output enable input (active LOW)
V_{CC}	16	supply voltage

6. Functional description

6.1 Function table

Table 3. Function table[1]

Control		Input		Output
$\overline{OE}$	S	nI0	nI1	nY
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		−0.5	+7	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V [1]	-	±20	mA
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V [1]	-	±20	mA
I_O	output current	$V_O = -0.5$ V to $V_{CC} + 0.5$ V	-	±35	mA
I_{CC}	supply current		-	+70	mA
I_{GND}	ground current		−70	-	mA
T_{stg}	storage temperature		−65	+150	°C
P_{tot}	total power dissipation	SO16 package [2]	-	500	mW
		TSSOP16 package [3]	-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO16 packages: above 70 °C, P_{tot} derates linearly with 8 mW/K.

[3] For TSSOP16 packages: above 60 °C, P_{tot} derates linearly with 5.5 mW/K.

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8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
74HC257-Q100						
V_{CC}	supply voltage		2.0	5.0	6.0	V
V_I	input voltage		0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	V
$\Delta t/\Delta V$	input transition rise and fall rates	V_{CC} = 2.0 V	-	-	625	ns
		V_{CC} = 4.5 V	-	1.67	139	ns
		V_{CC} = 6.0 V	-	-	83	ns
T_{amb}	ambient temperature		–40	-	+125	°C
74HCT257-Q100						
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_I	input voltage		0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	V
$\Delta t/\Delta V$	input transition rise and fall rates	V_{CC} = 4.5 V	-	1.67	139	ns
T_{amb}	ambient temperature		–40	-	+125	°C

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC257-Q100										
V_{IH}	HIGH-level input voltage	V_{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V_{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V_{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V_{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V_{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V_{OH}	HIGH-level output voltage	V_I = V_{IH} or V_{IL}								
		I_O = –20 μA; V_{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I_O = –20 μA; V_{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = –20 μA; V_{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I_O = –6.0 mA; V_{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I_O = –7.8 mA; V_{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V

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Table 6. Static characteristics *…continued*

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}								
		I_O = 20 μA; V_{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 20 μA; V_{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 20 μA; V_{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 6.0 mA; V_{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I_O = 7.8 mA; V_{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL}; $V_O = V_{CC}$ or GND; V_{CC} = 6.0 V	-	-	±0.5	-	±5.0	-	±10.0	μA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A; V_{CC} = 6.0 V	-	-	8.0	-	80	-	160	μA
C_i	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT257-Q100										
V_{IH}	HIGH-level input voltage	V_{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}; V_{CC} = 4.5 V								
		I_O = –20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = –6 mA	3.98	4.32	-	3.84	-	3.7	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}; V_{CC} = 4.5 V								
		I_O = 20 μA	-	0	0.1	-	0.33	-	0.4	V
		I_O = 6.0 mA	-	0.15	0.26	-	0.33	-	0.4	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL}; V_{CC} = 5.5 V; $V_O = V_{CC}$ or GND per input pin; other inputs at V_{CC} or GND; I_O = 0 A	-	-	±0.5	-	±5.0	-	±10	μA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	8.0	-	80	-	160	μA
ΔI_{CC}	additional supply current	$V_I = V_{CC}$ – 2.1 V; other inputs at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V; I_O = 0 A								
		per input pin; nI0, nI1 inputs	-	40	144	-	180	-	196	μA
		per input pin; $\overline{OE}$ input	-	135	486	-	608	-	662	μA
		per input pin; S input	-	70	252	-	315	-	343	μA
C_I	input capacitance		-	3.5	-	-	-	-	-	pF

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10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); For test circuit, see Figure 8.

Symbol	Parameter	Conditions	25 °C		–40 °C to +85 °C	–40 °C to +125 °C	Unit
			Typ	Max	Max	Max	
74HC257-Q100							
t_{pd}	propagation delay	nI0 to nY or nI1 to nY; see Figure 6 [1]					
		V_{CC} = 2.0 V	36	110	140	165	ns
		V_{CC} = 4.5 V	13	22	28	33	ns
		V_{CC} = 5.0 V; C_L = 15 pF	11	-	-	-	ns
		V_{CC} = 6.0 V	10	19	24	28	ns
		S to nY; see Figure 6					
		V_{CC} = 2.0 V	47	150	190	225	ns
		V_{CC} = 4.5 V	17	30	38	45	ns
		V_{CC} = 5.0 V; C_L = 15 pF	14	-	-	-	ns
		V_{CC} = 6.0 V	14	26	33	38	ns
t_{en}	enable time	$\overline{OE}$ to nY; see Figure 7 [2]					
		V_{CC} = 2.0 V	33	150	190	225	ns
		V_{CC} = 4.5 V	12	30	38	45	ns
		V_{CC} = 6.0 V	10	26	33	38	ns
t_{dis}	disable time	$\overline{OE}$ to nY; see Figure 7 [3]					
		V_{CC} = 2.0 V	41	150	190	225	ns
		V_{CC} = 4.5 V	15	30	38	45	ns
		V_{CC} = 6.0 V	12	26	33	38	ns
t_t	transition time	see Figure 6 [4]					
		V_{CC} = 2.0 V	14	60	75	90	ns
		V_{CC} = 4.5 V	5	12	15	18	ns
		V_{CC} = 6.0 V	4	10	13	15	ns
C_{PD}	power dissipation capacitance	per multiplexer; V_I = GND to V_{CC} [5]	45	-	-	-	pF
74HCT257-Q100							
t_{pd}	propagation delay	nI0 to nY or nI1 to nY; see Figure 6 [1]					
		V_{CC} = 4.5 V	16	30	38	45	ns
		V_{CC} = 5.0 V; C_L = 15 pF	13	-	-	-	ns
		S to nY; see Figure 6					
		V_{CC} = 4.5 V	20	35	44	53	ns
		V_{CC} = 5.0 V; C_L = 15 pF	17	-	-	-	ns
t_{en}	enable time	$\overline{OE}$ to nY; V_{CC} = 4.5 V; see Figure 7 [2]	15	30	38	45	ns
t_{dis}	disable time	$\overline{OE}$ to nY; V_{CC} = 4.5 V; see Figure 7 [3]	16	30	38	45	ns
t_t	transition time	V_{CC} = 4.5 V; see Figure 6 [4]	5	12	15	18	ns

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Table 7. Dynamic characteristics *...continued*

Voltages are referenced to GND (ground = 0 V); For test circuit, see Figure 8.

Symbol	Parameter	Conditions	25 °C		–40 °C to +85 °C	–40 °C to +125 °C	Unit
			Typ	Max	Max	Max	
C_{PD}	power dissipation capacitance	per multiplexer; V_I = GND to V_{CC} − 1.5 V [5]	45	-	-	-	pF

[1] t_{pd} is the same as t_{PHL}, t_{PLH}.

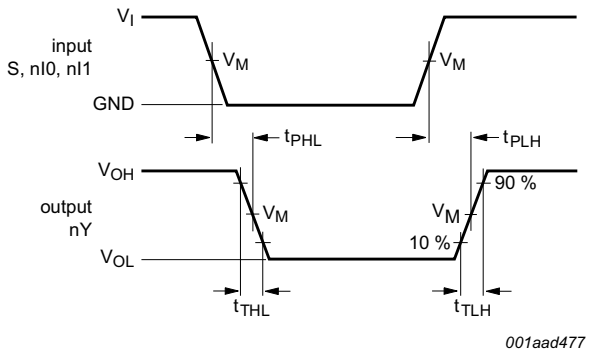
[2] t_{en} is the same as t_{PZH}, t_{PZL}.

[3] t_{dis} is the same as t_{PHZ}, t_{PLZ}.

[4] t_t is the same as t_{THL}, t_{TLH}.

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in V;
N = number of inputs switching;
$\sum(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms



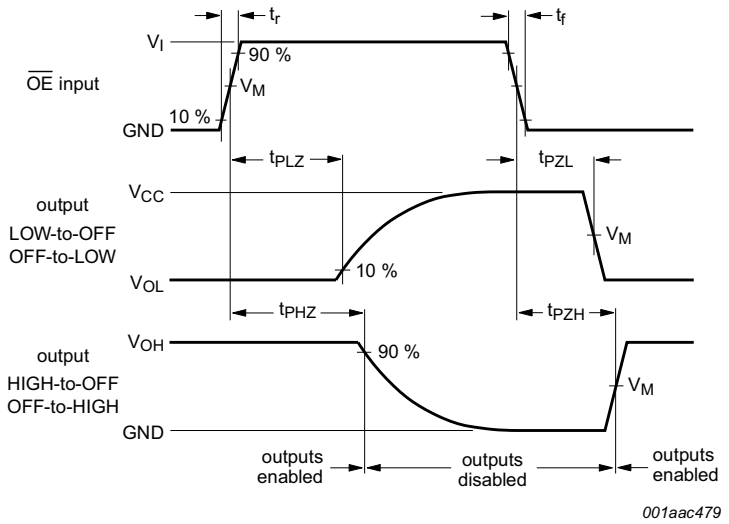
Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Propagation delays input (S, nI0, nI1) to output (nY) and output (nY) transition times

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Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

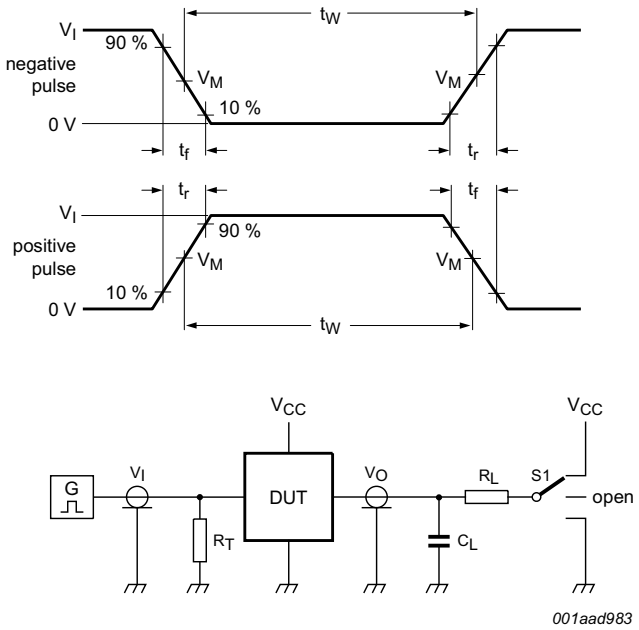
Fig 7. 3-state output enable and disable times

Table 8. Measurement points

Type	Input	Output
	V_M	V_M
74HC257-Q100	$0.5V_{CC}$	$0.5V_{CC}$
74HCT257-Q100	1.3 V	1.3 V

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Measurement points are given in Table 8 and test data is given in Table 9.

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistor.

Fig 8. Test circuit for measuring switching times

Table 9. Test data

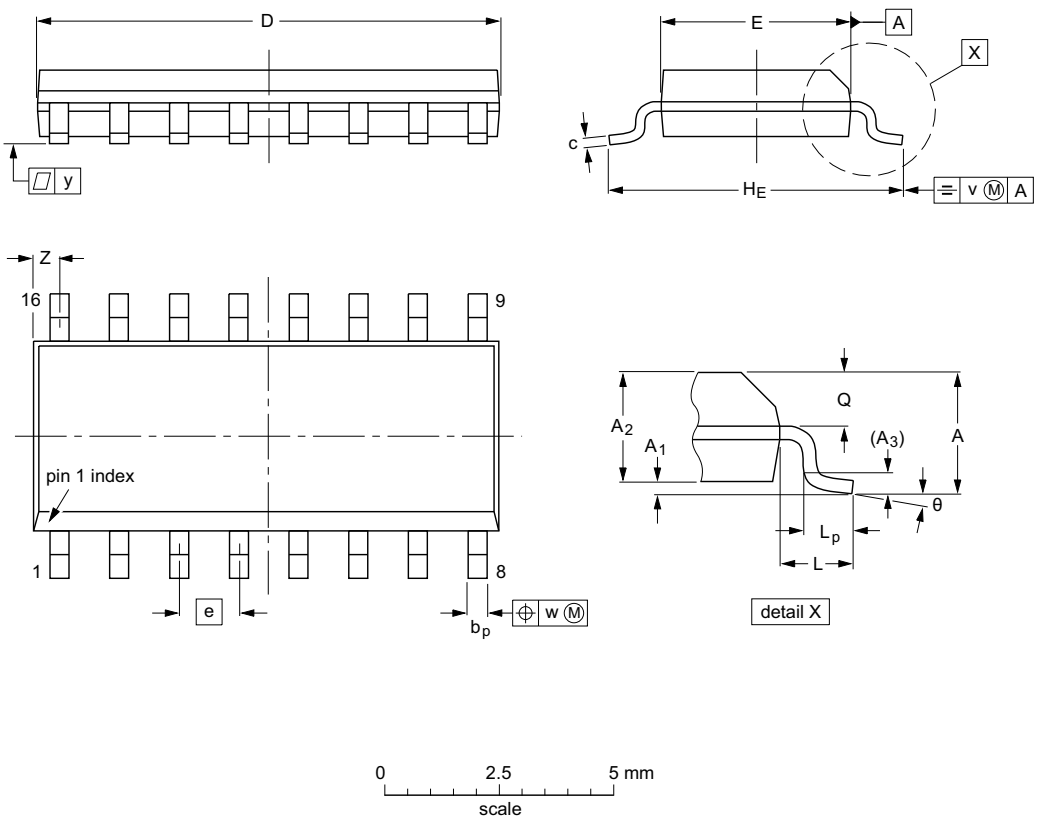
Type	Input		Load		Switch position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC257-Q100	V_{CC}	6 ns	50 pF	1 kΩ	open	GND	V_{CC}
74HCT257-Q100	3 V	6 ns	50 pF	1 kΩ	open	GND	V_{CC}

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12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

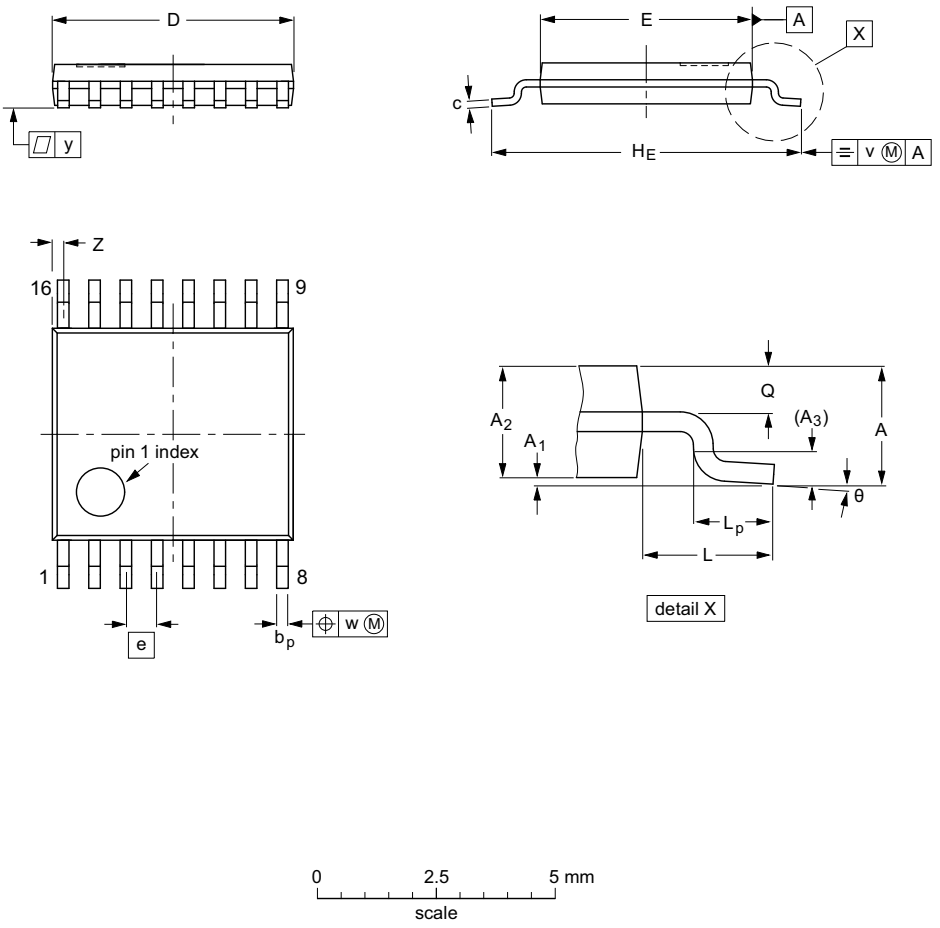
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig 9. Package outline SOT109-1 (SO16)

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TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig 10. Package outline SOT403-1 (TSSOP16)

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13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
MIL	Military

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT257_Q100 v.1	20150727	Product data sheet	-	-

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15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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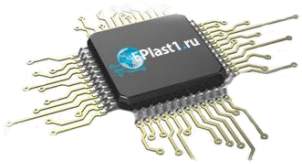
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